

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Reza A. Pagaila</td> <td>06/19/2009</td> </tr> <tr> <td>Byung Tai Do</td> <td>06/19/2009</td> </tr> <tr> <td>Shaungwu Huang</td> <td>06/19/2009</td> </tr> <tr> <td>Rajendra D. Pendse</td> <td>07/09/2009</td> </tr> </tbody> </table>		Name	Execution Date	Reza A. Pagaila	06/19/2009	Byung Tai Do	06/19/2009	Shaungwu Huang	06/19/2009	Rajendra D. Pendse	07/09/2009		
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RECEIVING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>STATS ChipPAC, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>10 Ang Mo Kio Street 65</td> </tr> <tr> <td>Internal Address:</td> <td>#05-17/20 Techpoint</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569059</td> </tr> </table>		Name:	STATS ChipPAC, Ltd.	Street Address:	10 Ang Mo Kio Street 65	Internal Address:	#05-17/20 Techpoint	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569059
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CORRESPONDENCE DATA													
<p>Fax Number: (602)748-4414</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 602-748-4408</p> <p>Email: main@plgaz.com</p> <p>Correspondent Name: Robert D. Atkins</p> <p>Address Line 1: 605 W. Knox Road</p> <p>Address Line 2: Suite 104</p> <p>Address Line 4: Tempe, ARIZONA 85284</p>													
ATTORNEY DOCKET NUMBER:	2515.0160												
NAME OF SUBMITTER:	Robert D. Atkins												

CH \$40.00 12492360

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PATENT
REEL: 022941 FRAME: 0129

Total Attachments: 5

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, REZA A. PAGAILA of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

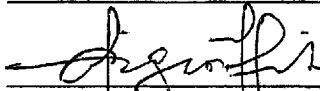
I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


Signature for REZA A. PAGAILA

Witnessed on this date:

19 JUNE 2009

Signature of Witness:



Printed Name of Witness:

DIOSCORO MERILO

Address of Witness:

BLK. 966 HOUSANG AVE. 9
#10-592, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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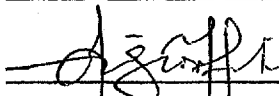


Signature for BYUNG TAI DO

Witnessed on this date:

19 JUNE 2009

Signature of Witness:



Printed Name of Witness:

DIOSCORO MERILLO

Address of Witness:

BLK. 966, HOUEANG AVE. 9

#10-592, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SHUANGWU HUANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING CONDUCTIVE PILLARS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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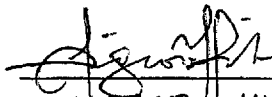


Signature for SHUANGWU HUANG

Witnessed on this date:

19 JUNE 2021

Signature of Witness:



Printed Name of Witness:

DI SCORIO MERILO

Address of Witness:

BLK. 966 HOUGANG AVE. A
#10-542, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, RAJENDRA D. PENDSE of Fremont, California, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in United States Application No. 12/492,360, filed June 26, 2009, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s)

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the aboveidentified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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Signature for RAJENDRA D. PENDSE

~~STATE OF CALIFORNIA)
COUNTY OF _____)~~

~~I, _____, a Notary Public in and for the County and State aforesaid, do hereby certify that RAJENDRA D. PENDSE, whose name is subscribed to the foregoing instrument, appeared before me this day in person and acknowledged that he/she signed, sealed and delivered the instrument as his/her free and voluntary act and deed for the uses and purposes therein set forth.~~

~~Given under my hand and notarial seal this _____ day of _____, 2009.~~

See Attached

Signature of Notary

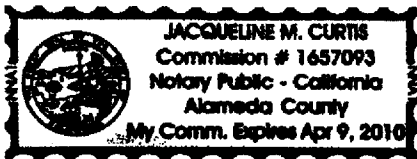
CALIFORNIA ALL-PURPOSE ACKNOWLEDGMENT

State of California

County of Alameda

On July 9, 2009 before me, Jacqueline M. Curtis, Notary Public

personally appeared Rajendra D. Pendse



who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Place Notary Seal Above

Signature

Signature of Notary Public

OPTIONAL

Though the information below is not required by law, it may prove valuable to persons relying on the document and could prevent fraudulent removal and reattachment of this form to another document.

Description of Attached Document

Title or Type of Document: Assignment + Agreement

Document Date: July 9, 2009 Number of Pages: 1

Signer(s) Other Than Named Above: N/A

Capacity(ies) Claimed by Signer(s)

Signer's Name: Rajendra D. Pendse

☒ Individual

☐ Corporate Officer — Title(s): _____

☐ Partner — ☐ Limited ☐ General

☐ Attorney in Fact

☐ Trustee

☐ Guardian or Conservator

☐ Other: _____

Signer Is Representing: _____

RIGHT THUMBPRINT
OF SIGNER
Top of thumb here



Signer's Name: _____

☐ Individual

☐ Corporate Officer — Title(s): _____

☐ Partner — ☐ Limited ☐ General

☐ Attorney in Fact

☐ Trustee

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☐ Other: _____

Signer Is Representing: _____

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